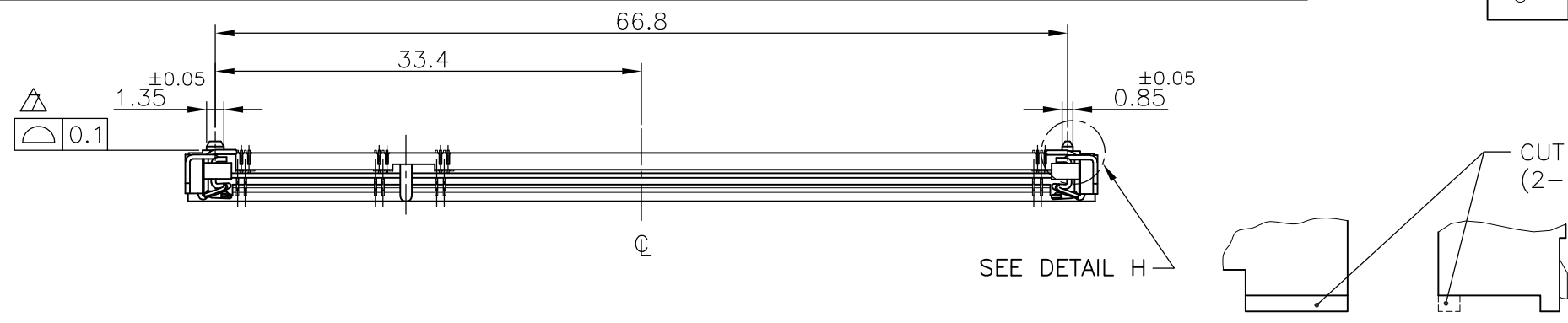
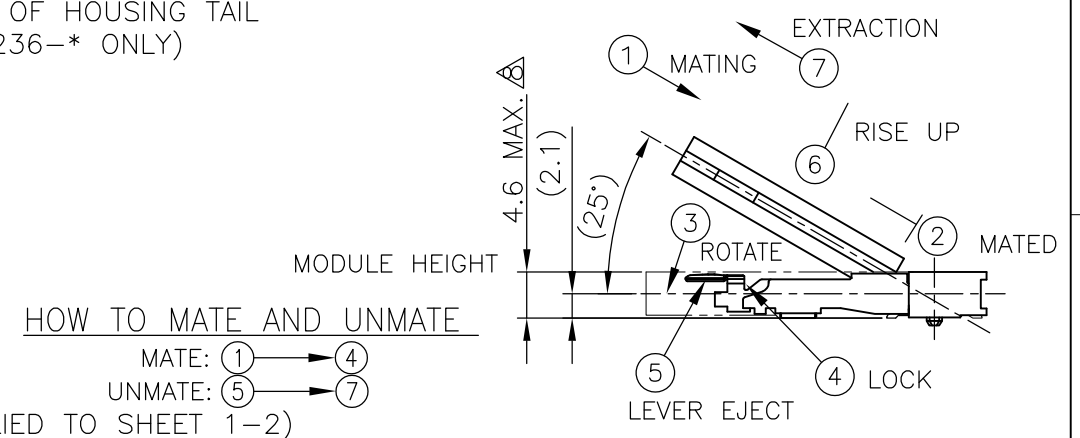


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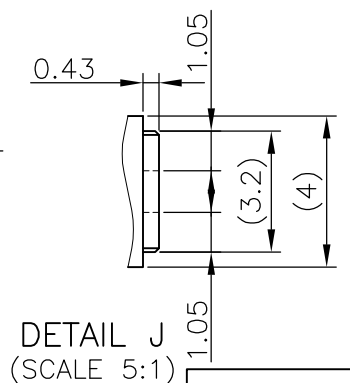
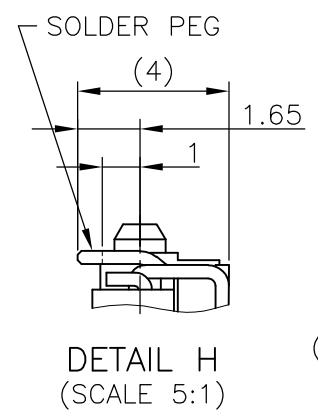
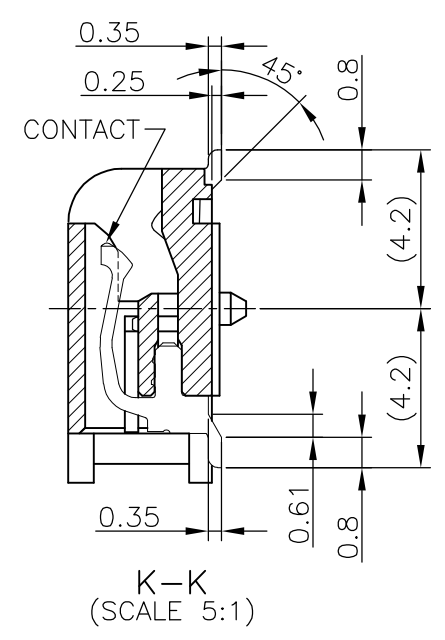
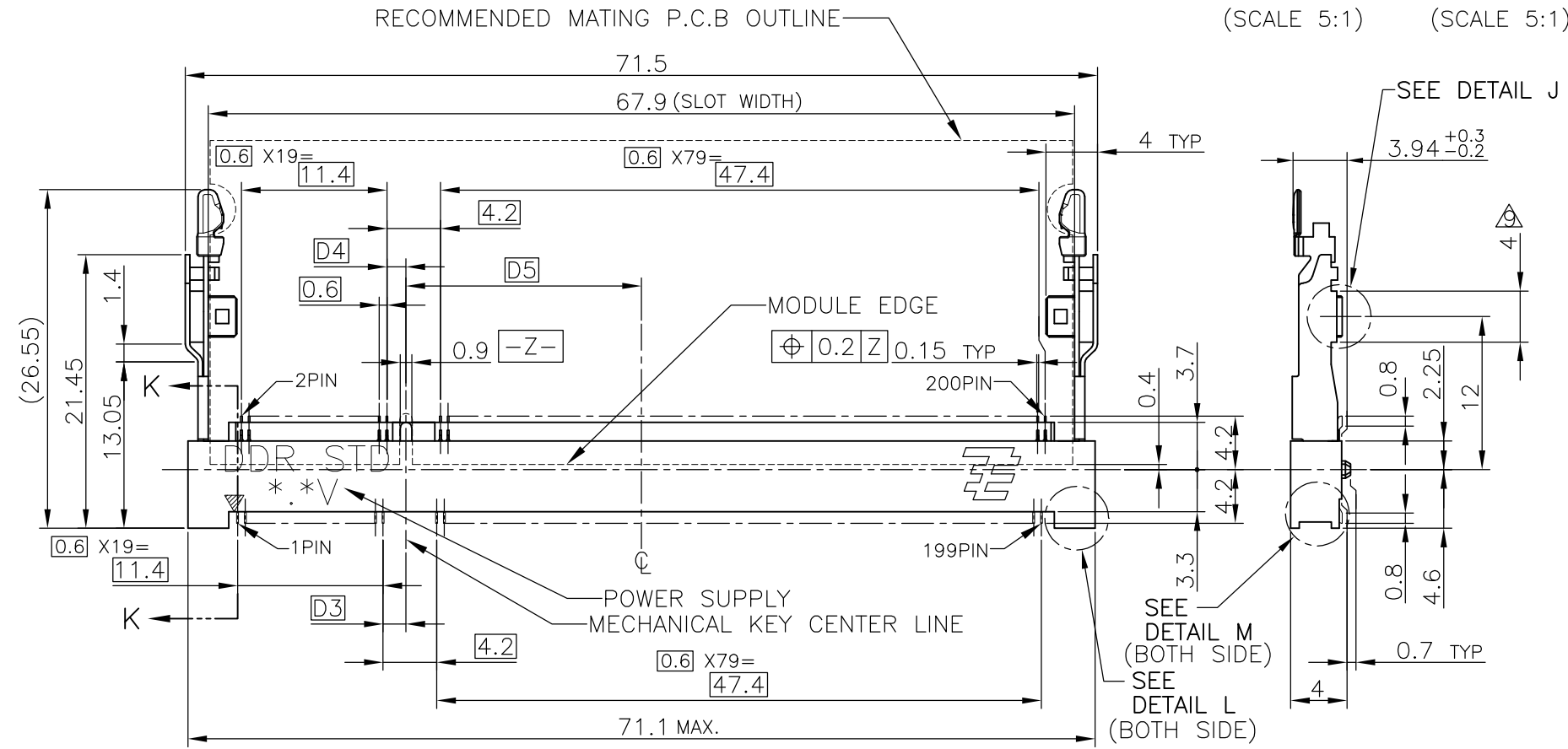
LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
J		R2	REVISED PER ECO-11-005033	26MAR11	RK HMR



DETAIL L (SCALE 5:1) DETAIL M (SCALE 5:1)



1. MATERIAL ; HOUSING: HIGH TEMPERATURE THERMO PLASTIC UL94V-0
 CONTACT: COPPER ARROY
 LOCK LEVER: STAINLESS STEEL
 Δ FINISH ; CONTACT AREA: GOLD FLASH ON 0.0013MIN ALL OVER NICKEL.
 SOLDERING AREA: GOLD FLASH PLATING.
 LOCK LEVER: TIN PLATING.
 Δ MECHANICAL KEY POSITION OF CONNECTOR SEE TABLE.
 Δ TOLERANCES NON-CUMULATIVE.
 Δ NOT TO SCALE.
 Δ INSIDE MUST BE RESIST COAT EXCEPT SOLDER PATTERN.
 Δ COPLANARITY : 0.1 MAX.
 Δ THE FLOATING VALUE BY SOLDERING IS NOT INCLUDED.
 Δ NOT MATING CONDITION.
 10 IF THE MODULE DOESN'T INSERT AND LOCK IN THE LATCH SMOOTHLY,
 OPEN WIDE BOTH LATCHES BY MANUAL. AND THE MODULE MUST BE
 INSERTED AND LOCKED IN THE LATCH.
 Δ FINISH ; CONTACT AREA: GOLD 0.00076MIN PLATING ON 0.0013MIN ALL
 OVER NICKEL.
 SOLDERING AREA: GOLD FLASH PLATING.
 LOCK LEVER: TIN PLATING.



GENERAL TOLERANCE
 10 ≥ : ±0.2
 30 ≥ > 10: ±0.25
 100 ≥ > 30: ±0.3
 ANGLES: ±3'

FINISH	TOOLING STATUS	REMARK	POWER SUPPLY	D5	D4	D3	POS	PART NO.
Δ	AVAILABLE	POROSITY SEALING	1.8V (DDR2)	17.55	2.4	2.7	200	1827236-6
Δ	AVAILABLE	CUT OUT OF POROSITY SEALING	1.8V (DDR2)	17.55	2.4	2.7	200	3-1827236-4
Δ	AVAILABLE	CUT OUT OF HOUSING TAIL	1.8V (DDR2)	17.55	2.4	2.7	200	2-1827236-4
Δ	AVAILABLE	BOSSLESS	1.8V (DDR2)	17.55	2.4	2.7	200	1-1827236-4
Δ	AVAILABLE	— —	1.8V (DDR2)	17.55	2.4	2.7	200	1827236-4
— —	NOT AVAILABLE	— —	2.5V (DDR1)	18.45	1.5	1.8	200	—

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DWN	B.WONG	20JUL10
CHK	C.WANG	20JUL10
APVD	S.YAO	20JUL10

PRODUCT SPEC: 108-5701
 APPLICATION SPEC

STE TE Connectivity

NAME: DDR1 & DDR2 SODIMM SOCKET 0.6mm PITCH
 200POS LOW PROFILE STANDARD TYPE
 (LATCH DIRECT SOLDERING TYPE)

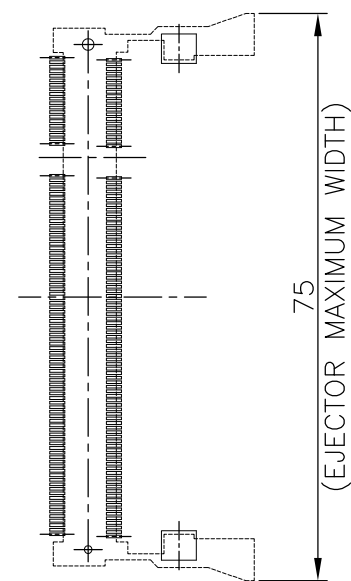
SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A3	00779	C-1827236	

WEIGHT: 3.2 g

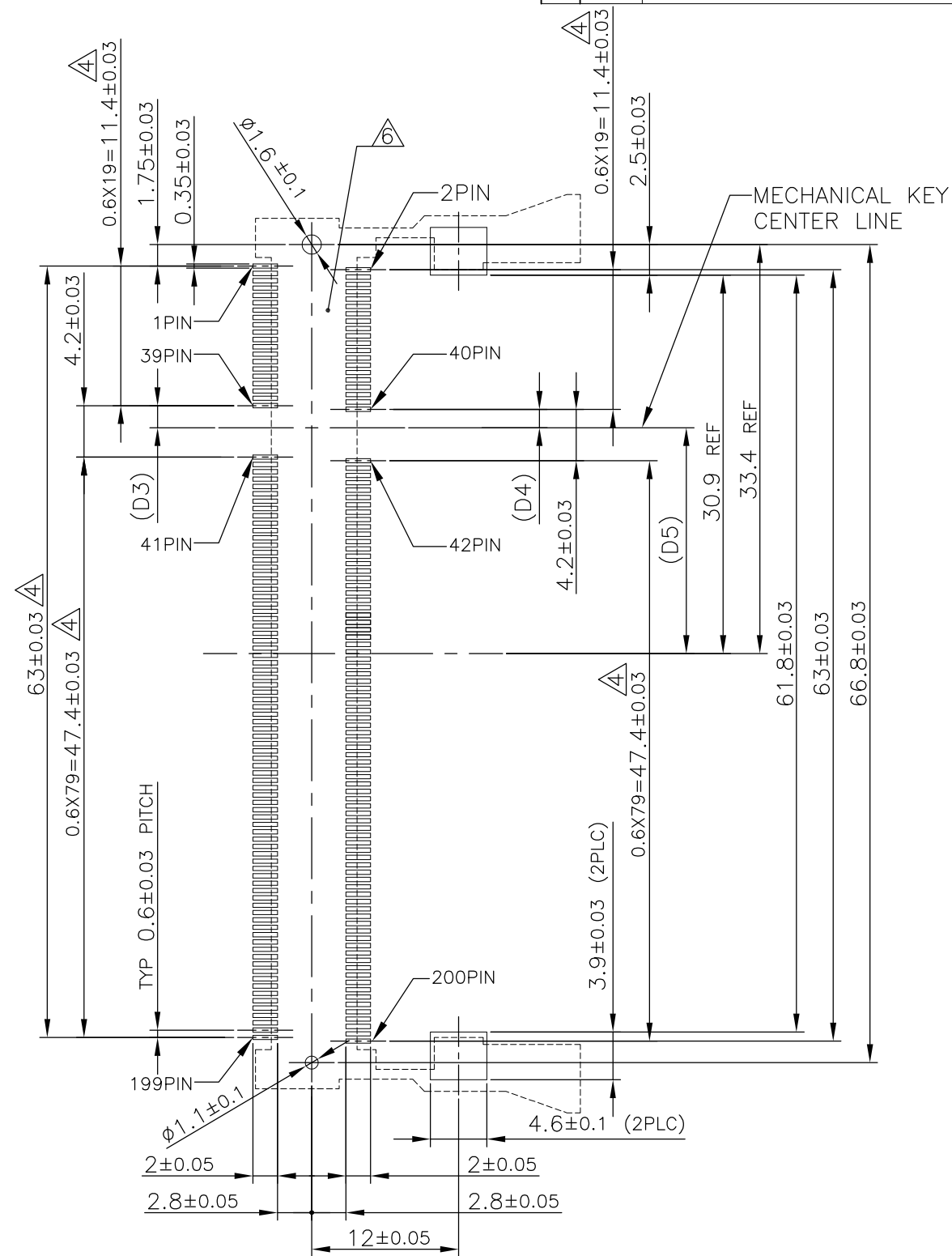
CUSTOMER DRAWING SCALE: 2:1 SHEET: 1 OF 4 REV: R2

LOC	DIST	REVISIONS		
J		P	LTR	DESCRIPTION
		-	-	SEE SHEET 1
				DATE
				DWN
				APVD

REFERENCE P.C. BOARD PATTERN LAYOUT (CONNECTOR MOUNTING SIDE)



REAL SIZE (SCALE 1:1)

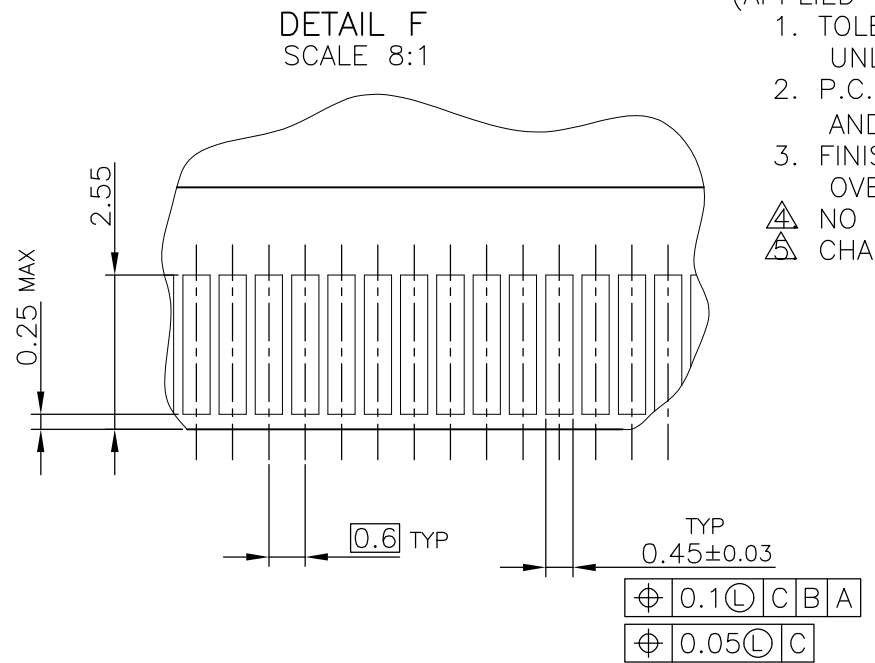
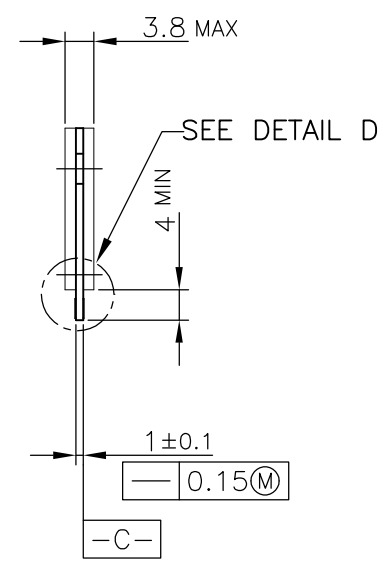
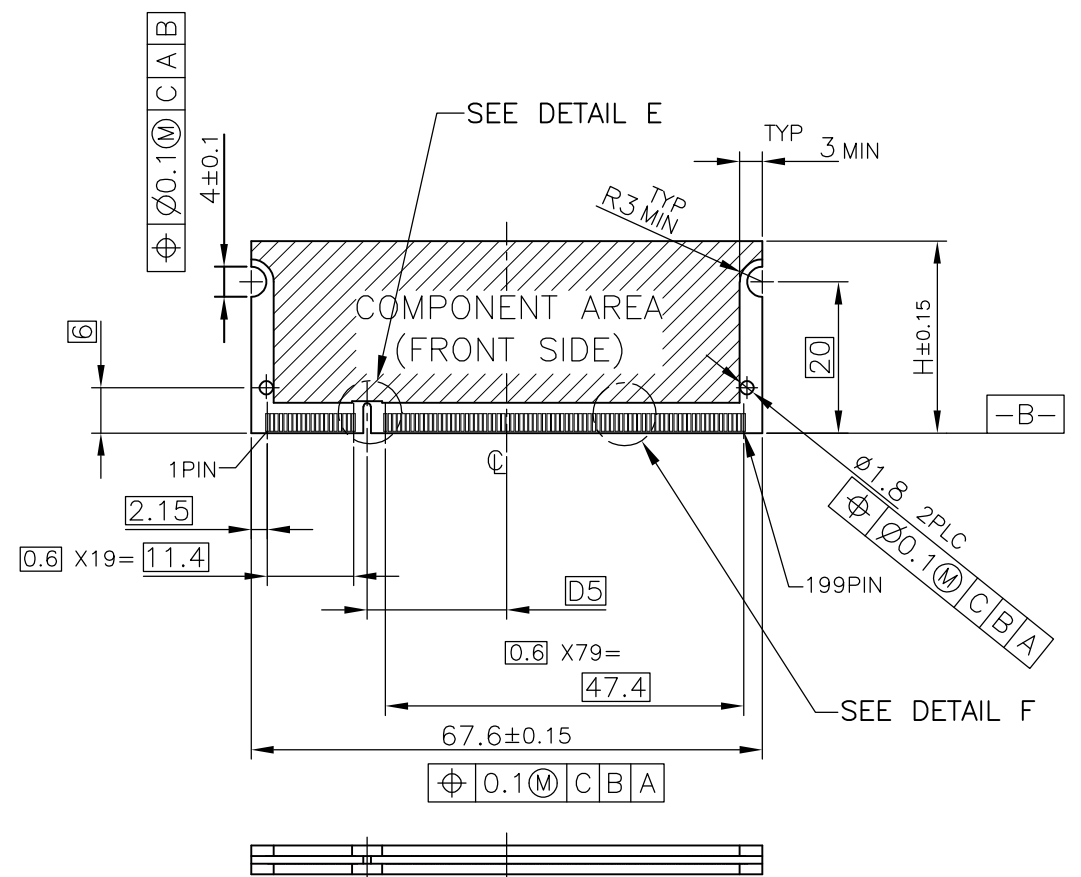


1.8V	17.55	2.4	2.7
2.5V	18.45	1.5	1.8
POWER SUPPLY	D5	D4	D3

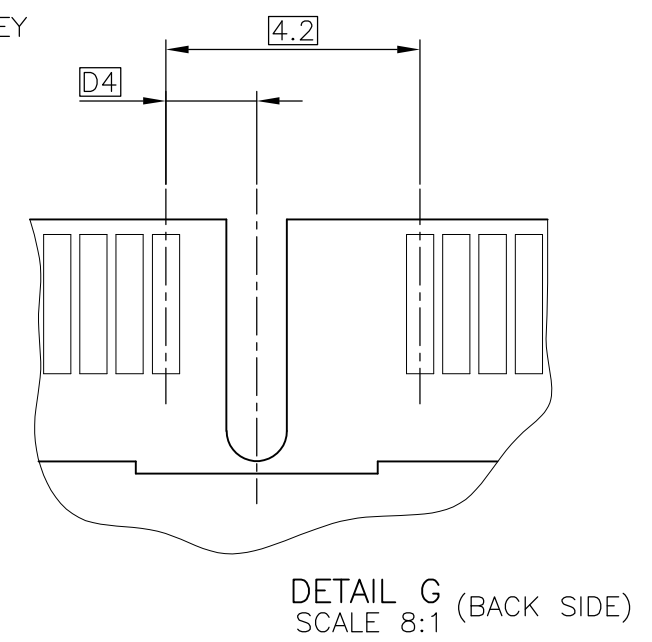
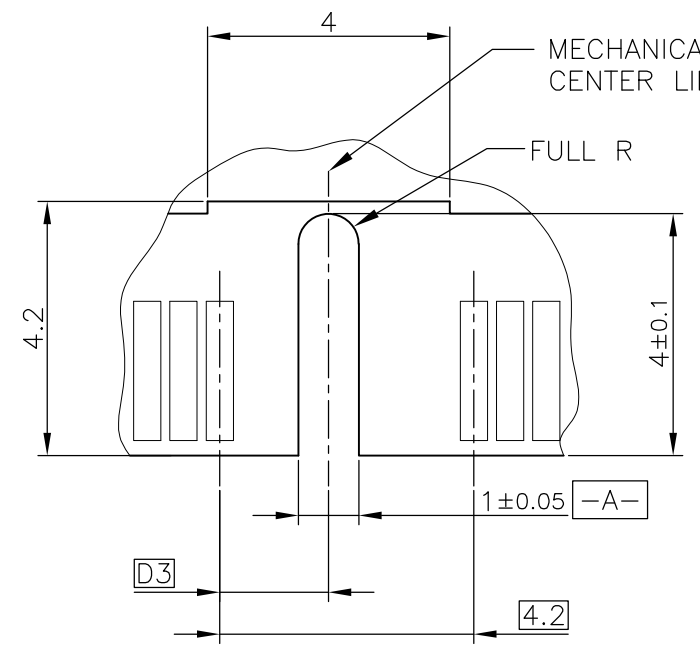
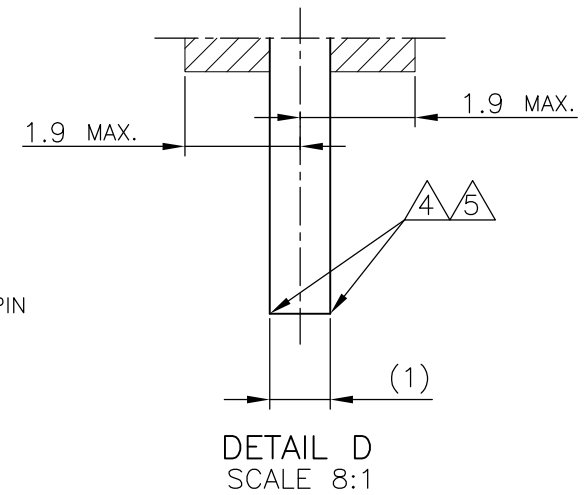
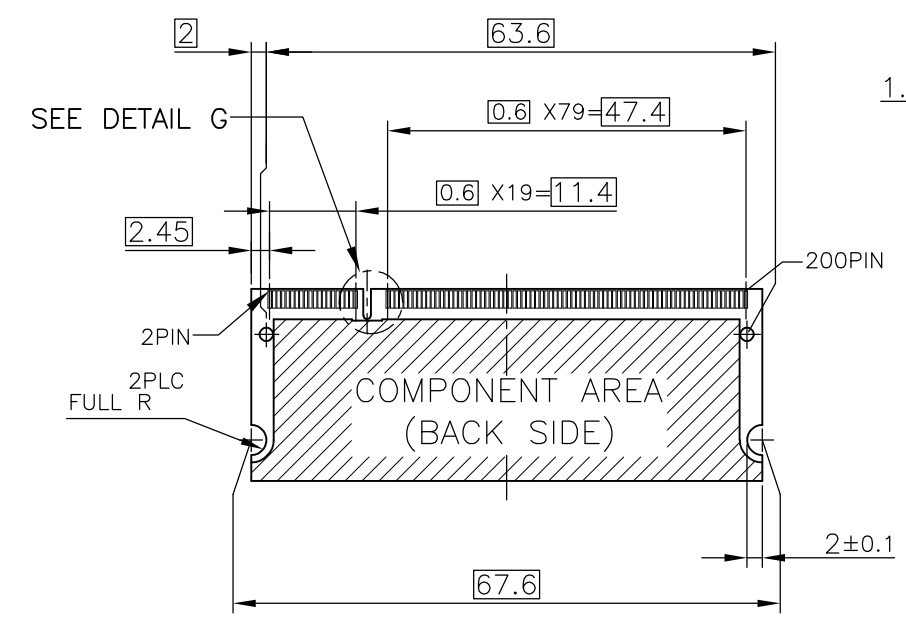
THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	STE TE Connectivity	
DIMENSIONS: MM		CHK		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD	NAME	
0 PLC ±		PRODUCT SPEC	DDR1 & DDR2 SODIMM SOCKET 0.6mm PITCH	
1 PLC ±		APPLICATION SPEC	200POS LOW PROFILE STANDARD TYPE	
2 PLC ±		WEIGHT	(LATCH DIRECT SOLDERING TYPE)	
3 PLC ±		CUSTOMER DRAWING	SIZE	RESTRICTED TO
4 PLC ±			A3	
ANGLES ±		CAGE CODE	DRAWING NO	
FINISH		00779	C-1827236	
		SCALE 2:1		SHEET 2 OF 4
		REV R2		

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LOC	DIST	REVISIONS					
J		P	LTR	DESCRIPTION	DATE	DWN	APVD
		-		SEE SHEET 1	-	-	-



- (APPLIED TO SHEET 3)
1. TOLERANCES ON ALL DIMENSIONS ±0.15 UNLESS OTHERWISE SPECIFIED.
 2. P.C.BOARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION.
 3. FINISH OF PAD : GOLD PLATING 0.00076 MIN. OVER Ni PLATING 0.002MIN.
- ▲ NO BURR
 △ CHAMFER 0.25 MAX x 45° IF EXIST.



RECOMMENDED MATING P.C.B CONFIGURATION

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN
DIMENSIONS: MM		CHK
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD
0 PLC	±	PRODUCT SPEC
1 PLC	±	APPLICATION SPEC
2 PLC	±	WEIGHT
3 PLC	±	CUSTOMER DRAWING
4 PLC	±	
ANGLES	±	
FINISH		

31.75	1.8V	17.55	2.4	2.7
25.4	2.5V	18.45	1.5	1.8
H	POWER SUPPLY	D5	D4	D3

STE TE Connectivity

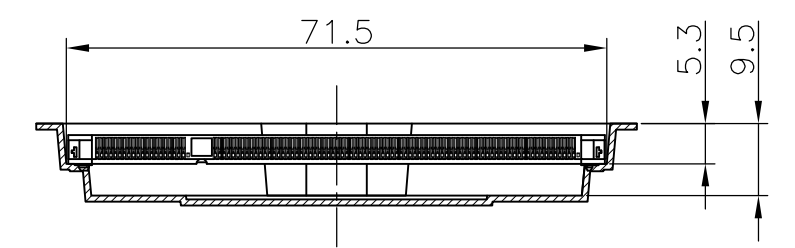
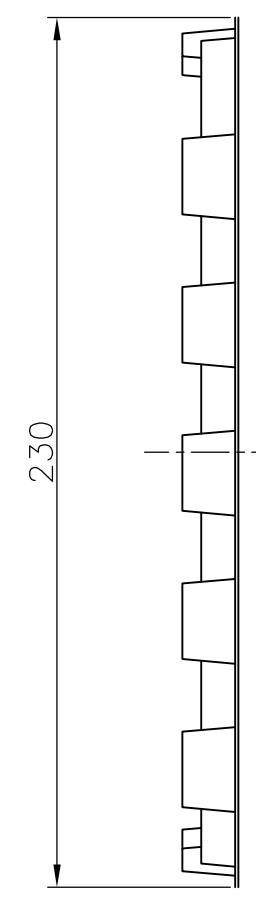
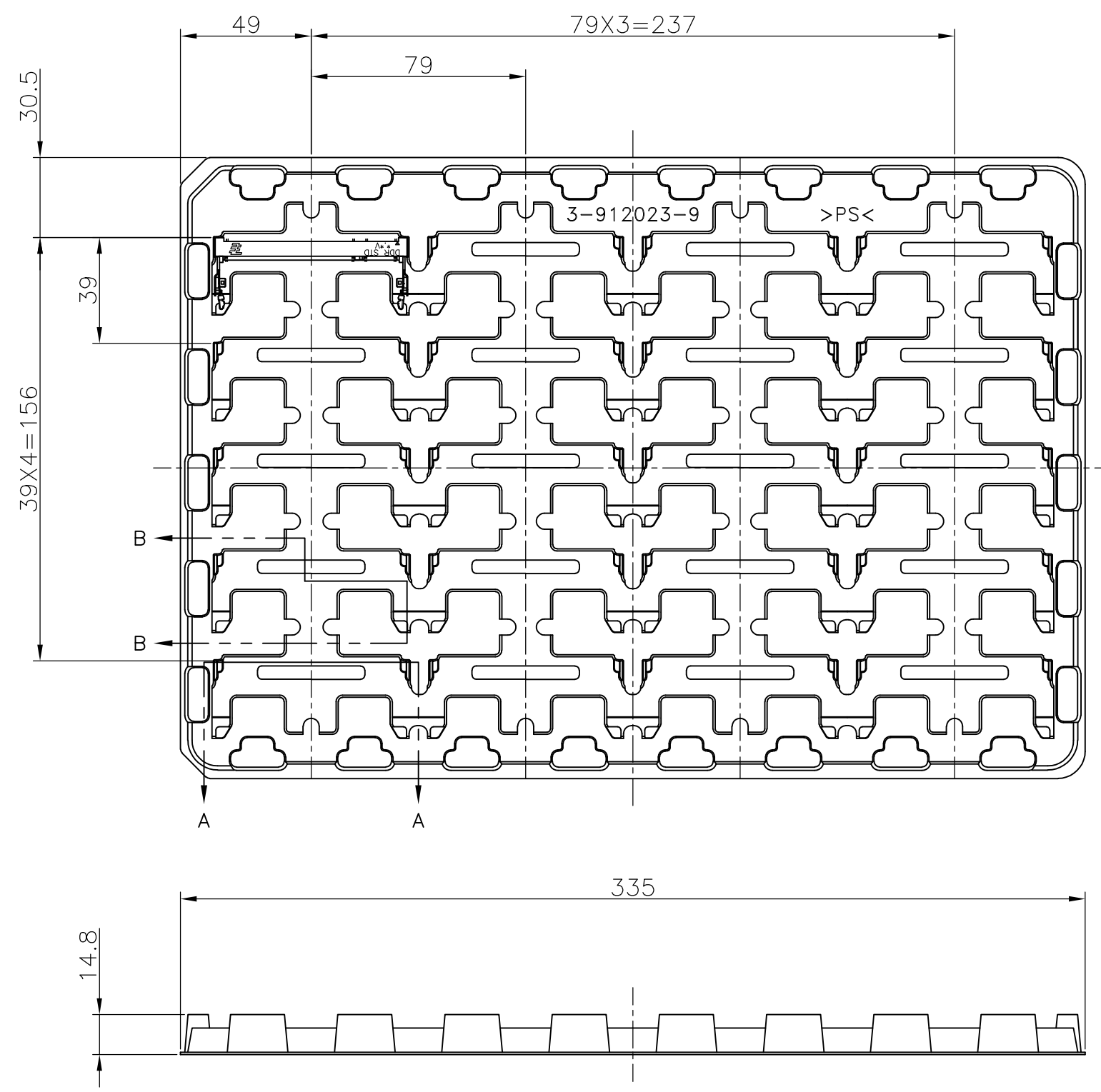
NAME: DDR1 & DDR2 SODIMM SOCKET 0.6mm PITCH 200POS LOW PROFILE STANDARD TYPE (LATCH DIRECT SOLDERING TYPE)

SIZE: A3 CAGE CODE: 00779 DRAWING NO: C-1827236 RESTRICTED TO: []

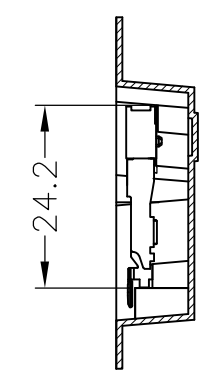
SCALE: 2:1 SHEET: 3 OF 4 REV: R2

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LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
J		SEE SHEET 1	-	-	-



A-A
SCALE 1:1
(180DEG. ROTATE)



B-B
SCALE 1:1

1. THE DIRECTION OF EACH CONNECTOR ON A TRAY IS REFERRED TO THIS DRAWING.
2. GENERAL TOLERANCE : ±0.5

AVAILABLE	20EA/TRAY	1827236-6
AVAILABLE	20EA/TRAY	3-1827236-4
AVAILABLE	20EA/TRAY	2-1827236-4
AVAILABLE	20EA/TRAY	1-1827236-4
AVAILABLE	20EA/TRAY	1827236-4
NOT AVAILABLE	20EA/TRAY	-
TOOLING STATUS	QTY	P/N

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	TE Connectivity NAME SEMI-HARD TRAY ASSY DDR1 & DDR2 SODIMM SOCKET 200P LOW PROFILE STANDARD TYPE (LATCH DIRECT SOLDERING TYPE)				
DIMENSIONS: MM		CHK					
		APVD					
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ± 3 PLC ± 4 PLC ± ANGLES ± FINISH ±		PRODUCT SPEC					
MATERIAL		APVD	APPLICATION SPEC	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
		WEIGHT	A300779		C-1827236		
CUSTOMER DRAWING			SCALE	1:2	SHEET	4 OF 4	REV R2